

MMSZ4686

General Description

Half watt, General purpose, Medium Current Surface Mount Zener in the SOD-123 package. The SOD-123 package has the same footprint as the glass mini-melf (LL-34) package & provides a convenient alternative to the Leadless package.

Features

- Compact surface mount with same footprint as mini-melf
- 500mW rating on FR-4 or FR-5 board.
- Class 3 ESD rating (>16kV) per Human Body Model

Ordering

- 7 inch reel (178mm); 8mm Tape; 3,000 units per reel.

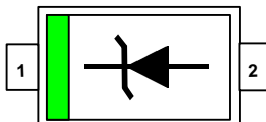
Absolute Maximum Ratings (note 1) $T_A=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
T_{STG}	Storage Temperature	-55 ~ 150	$^\circ\text{C}$
T_J	Maximum Junction Temperature	-55 ~ 150	$^\circ\text{C}$
P_D	Total Power Dissipation at 25°C Derate above 25°C	500 6.7	mW mW/ $^\circ\text{C}$
R_{QJA}	Thermal Resistance Junction to Ambient	340	$^\circ\text{C/W}$
R_{QJL}	Thermal Resistance Junction to Lead	150	$^\circ\text{C/W}$
ΔV_Z	Maximum Voltage Change (note 2)	970	mV
Lead Solder Temperature (Max 10 second duration)		260	$^\circ\text{C}$
Nominal Zener Voltage (V_Z) at 50 μA		3.9	V

Note 1: These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Note 2: Voltage change is equal to the difference between V_Z at 100 μA and V_Z at 10 μA .

Top Mark: CN
1: Cathode
2: Anode



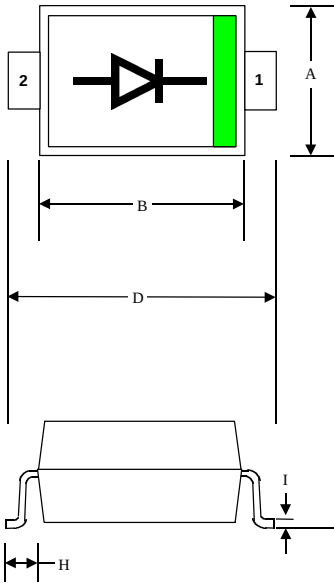
Electrical Characteristics $T_A=25^\circ\text{C}$ unless otherwise noted

Symbol	Characteristics	Test Conditions	Min.	Max.	Units
V_Z	Zener Voltage	$I_{ZT} = 50\mu\text{A}$ D.C	3.71	4.10	V
I_R	Reverse Leakage	$V_R = 2.0\text{V}$		5.0	μA
V_F	Forward Voltage	$I_F = 10\text{mA}$		900	mV
ΔV_Z	Delta Zener Voltage (Note 2)	$I_{ZT} = 100\mu\text{A}$ to 10 μA		970	mV

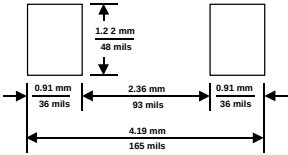
SOD-123 PACKAGE

PACKAGE CODE = (D6)
Fairchild Semiconductor's Criteria

Corrected March 11, 1998



Actual Size DIM	MIN (mils)	MAX (mils)	MIN (mm)	MAX (mm)
A	55	71	1.400	1.800
B	100	112	2.550	2.850
C	34.6	46	0.880	1.180
D	141.7	153.5	3.600	3.900
E	----	----	-----	-----
F	21.5	27.5	0.546	0.70
G	0.5	4	0.0135	0.1015
H	12.7	----	0.322	-----
I	3.7	7.7	0.095	0.195



SOD-123 LAND PADS

TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

ACEx™	FACT™	ImpliedDisconnect™	PACMAN™	SPM™
ActiveArray™	FACT Quiet Series™	ISOPLANAR™	POP™	Stealth™
Bottomless™	FAST®	LittleFET™	Power247™	SuperSOT™-3
CoolFET™	FASTr™	MicroFET™	PowerTrench®	SuperSOT™-6
CROSSVOLT™	FRFET™	MicroPak™	QFET™	SuperSOT™-8
DOME™	GlobalOptoisolator™	MICROWIRE™	QS™	SyncFET™
EcoSPARK™	GTO™	MSX™	QT Optoelectronics™	TinyLogic®
E ² CMOS™	HiSeC™	MSXPro™	Quiet Series™	TruTranslation™
EnSigna™	I ² C™	OCX™	RapidConfigure™	UHC™
Across the board. Around the world.™		OCXPro™	RapidConnect™	UltraFET®
The Power Franchise™		OPTOLOGIC®	SILENT SWITCHER®	VCX™
Programmable Active Droop™		OPTOPLANAR™	SMART START™	

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.